# DuPont 7484R

**AgPd Conductor Composition** 

## EUROPEAN TECHNICAL DATASHEET

All values reported here are results of experiments in our laboratories intended to illustrate product performance potential with a given experimental design. They are not intended to represent the product's specifications, details of which are available upon demand

## **Product Description**

DuPont 7484R Ag/Pd conductor is intended to be applied to ceramic substrates by screen printing and fired in a conveyor furnace in an air (oxidising) atmosphere.

It has been developed to form interconnection tracks and pads for component and lead attachment, in hybrid microcircuits and networks.

## **Product Benefits :**

- Fine line resolution
- Minimal spreading after printing
- Thin, dense fired films
- Optimised for 30 minute 850°C firing profile
- Excellent solderability on both alumina and 5704 or QM44 dielectric
- Suitable for 250µm Al wire bonding
- Excellent aged adhesion on both alumina and 5704 or QM44 dielectric
- Suitable for use in fuel sensors
- Phthalate, Cadmium, Nickel oxide free\*

\* Phthalate, Cadmium and Nickel oxide 'free' as used herein means that cadmium, phthalate and nickel oxide are not intentional ingredients in and are not intentionally added to the referenced product. Trace amounts however may be present

## **Design Notes**

When processed under the recommended conditions, 7484R causes no significant shifts in resistivity or TCR when used to terminate HS80 Series resistors.

7484R is compatible with 5704 or QM44 dielectric when separately fired. Cofiring of 7484R on top of dielectric is not recommended.

Overlaps of 7484R Ag/Pd with 6160 Ag on top of dielectric performance is dependant on the print sequence and quantity of refiring. Overlaps of 7484R Ag/Pd with Au conductor on top of dielectric: print 7484R Ag/Pd over Au conductor to avoid incompatibility.

To achieve optimum print resolution the following printing parameters are suggested: 325 mesh stainless steel screen



with a tension of 30N/cm, emulsion thickness of  $12\mu$ m, a print speed of 12.5cm/s with a 70 durometer shore hardness squeegee at an angle of attack of 45°, snap-off of 1.0mm for a 25 x 10cm screen.

## **Processing Summary**

## Screen Type

325 mesh stainless steel screen with a 12 $\mu$ m emulsion build up. Printing speeds of up to 25cm/s may be used. (See design notes for fine line printing)

#### • Drying

Allow prints to level for over 10 minutes at room temperature, then dry for  $\geq$  10 -15 minutes at 150°C

• Firing

850°C peak held for 10 minutes on 30 or 60 minute cycle in an air atmosphere

## **TABLE 1. TYPICAL PHYSICAL PROPERTIES**

Viscosity (Pa.s.)	150 - 230
(Brookfield HBT,10rpm, SC4-	
14/6R utility cup and spindle,25°C±	0.2°C)
Coverage [cm²/g]	85-95
Based on fired thickness of 11µm	
Shrinkage [%]	
Wet or Dry	~40%
Dried to Fired	~50%
Thinner	4553
Shelf Life (months)	6

## Compatibility

Whilst DuPont has tested this composition with the materials specified above and the recommended processing conditions, it is impossible or impractical to cover every combination of materials, customer processing conditions and circuit layouts.

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It is therefore essential that customers thoroughly evaluate the material in their specific situations in order to completely satisfy themselves with the overall quality and suitability of the composition for its intended application (s).

## **Storage and Shelf Life**

Containers may be stored in a clean, stable environment at room temperature (between  $5^{\circ}C - 30^{\circ}C$ ) with their lids tightly sealed. Storage in high temperature (<30°C) or in freezers (temperature <0°C) is NOT recommended as this could cause irreversible changes in the material. The shelf life of compositions in factory-sealed (unopened) containers between ( $5^{\circ}C - 30^{\circ}C$ ) is 6 months from date of shipment.

## **Substrates**

Substrates of different compositions and from various manufacturers may result in variations in performance properties

#### Thinner

7484R composition is optimized for screen printing and thinning is not normally required. Use the DuPont recommended thinner for slight adjustments to viscosity or to replace evaporation losses. The use of too much thinner or the use of a non recommended thinner may affect the rheological behaviour of the material and its printing characteristics. Please refer to table 1.Typical Physical Properties'

## Printing

The composition should be thoroughly mixed before use. This is best achieved by slow, gentle hand stirring with a clean burr-free spatula (flexible plastic or stainless steel) for about 1-2 minutes. Care must be taken to avoid air entrapment. Printing should be performed in a well ventilated area. Additional information on requirements for printing areas is contained in DuPont Technical Guide EUT 7.3 'Processing-Screen Printing Rooms' available on request.

Note: optimum printing characteristics are generally achieved in the room temperature range of 20°C-23°C. It is therefore important that the material, in its container, is at the temperature prior to commencement of printing. Class 10,000 printing area is recommended for building complex hybrids and multilayer circuits, otherwise severe yield losses could occur. Refer to 'Processing Summary'.

## Drying

Allow prints to level at room temperature, then dry in a well ventilated oven or conveyor dryer. Refer to 'Processing Summary'.

#### **Firing**

Fire in well ventilated belt, conveyor furnace or static furnace. Air flows and extraction rates should be optimized to ensure that oxidizing conditions exist within the muffle and that no exhaust gases enter the room.

Full information on requirements for firing is contained in DuPont Technical Guide EUT 7.4 'Process Guide-Firing'. Refer to 'Processing Summary'.

## General

Performance will depend to a large degree on care exercised in screen printing. Scrupulous care should be taken to keep the composition, printing screens and other tools free of metal contamination. Dust, lint and other particulate matter may also contribute to poor yields.

## **Safety and Handling**

DuPont thick film compositions are intended for use in an industrial environment by trained personnel. All appropriate health/ safety regulations regarding storage, handling and processing of such materials should be complied with. For information on health / safety regulations please refer to the specific product MSDS and to the DuPont Safety Guide EUT 7.1 'Practical Safe Handling of Thick Film Compositions'.

## **CHART 1. FIRING PROFILE**







## **TABLE 2. TYPICAL FIRED PROPERTIES<sup>1</sup>**

Line/Space resolution( μm) Fired Thickness (μm) Resistivity on alumina [mΩ/□] (@ 12μm fired thickness)	≥150 8 –13 15 –30
Solder Acceptance <sup>2</sup>	11
62Sn/36Pb/2Ag@220°C	≥96% coverage
Solder Leach Resistance	
62Sn/36Pb/2Ag @230°C	≥7 cycles
Adhesion (x5firings)[N] <sup>3</sup>	
Initial	≥20
Aged 1000hrs@ 150°C	≥20

#### **Test Procedure**

1 Typical properties are based on laboratory data using recommended processing procedures. Unless expressly noted elsewhere the following processing conditions have been used:

Printing: 200 mesh stainless steel screen, 10-14 $\!\mu m$  emulsion thickness

Firing: 3x 30 minute cycles to a peak temperature of 850°C for 10 minutes

Tested on 96% alumina substrates and on 5704 dielectrics

2 Using Alpha 611 flux. Solder coverage measured after a 5s dip in solder. A leaching cycle is represented by a 10s dip in solder and tested on  $500\mu m$  lines. See soldering test procedure for details (H-1.12)

3 90° wire peel test on 2mmx 2mm pads soldered with 62Sn/36Pb/2Ag solder at 220°C and using a mildly activated Alpha 611. See wire peel adhesion test procedure for details (E-3.12)

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L-14587 07/2011

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